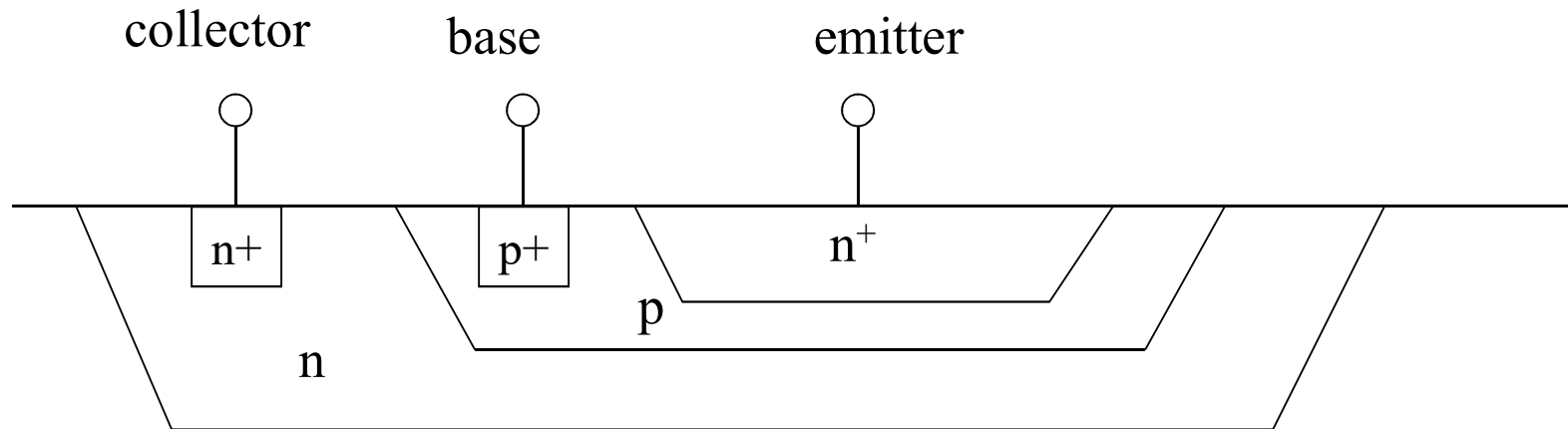


Bipolar transistors, Thyristors, and Latch-up

bipolar transistors

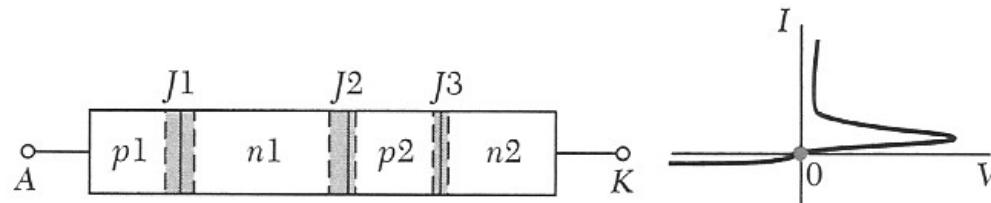
npn transistor



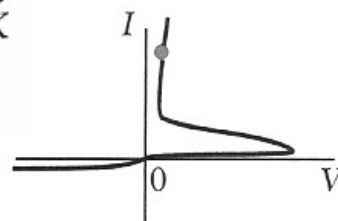
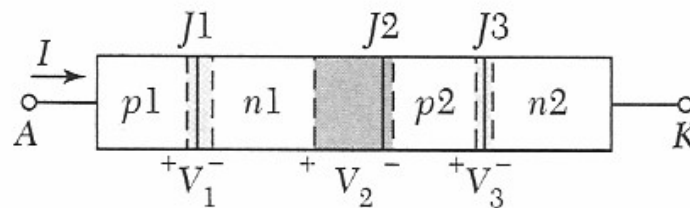
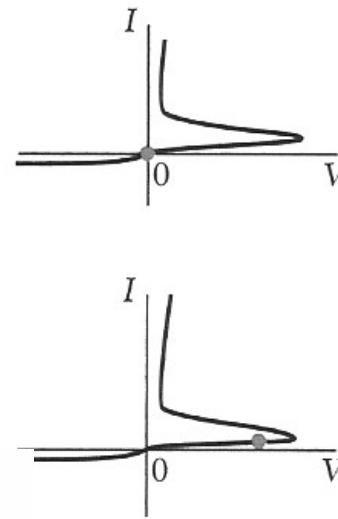
lightly doped p substrate

Used in front-end high-frequency receivers (mobile telephones).

Thyristors

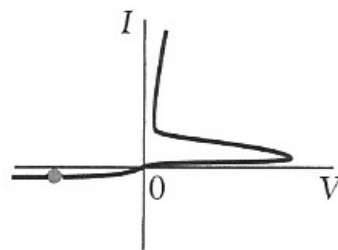
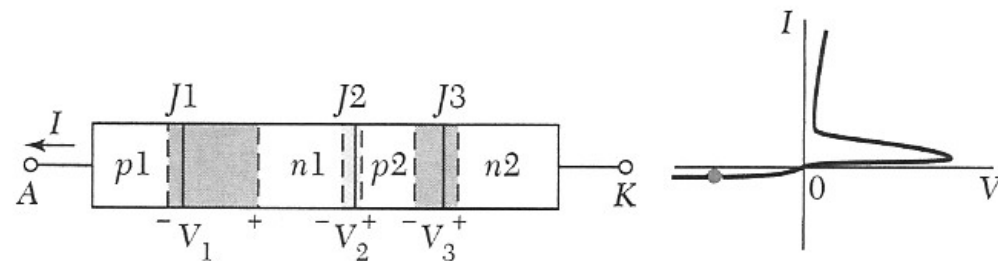


Forward blocking

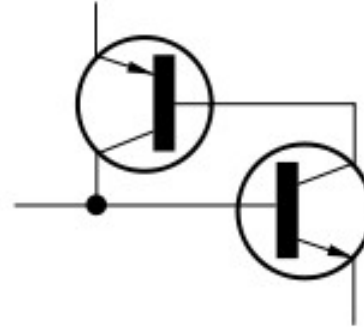
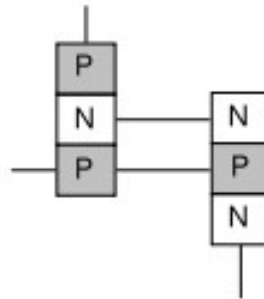
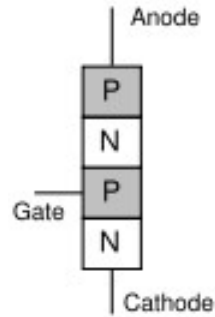


Forward conducting

Reverse blocking

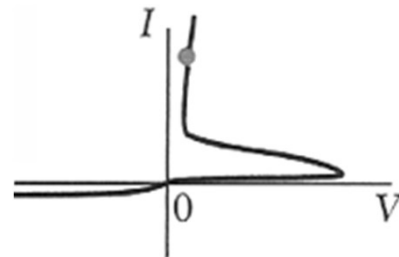


Thyristors

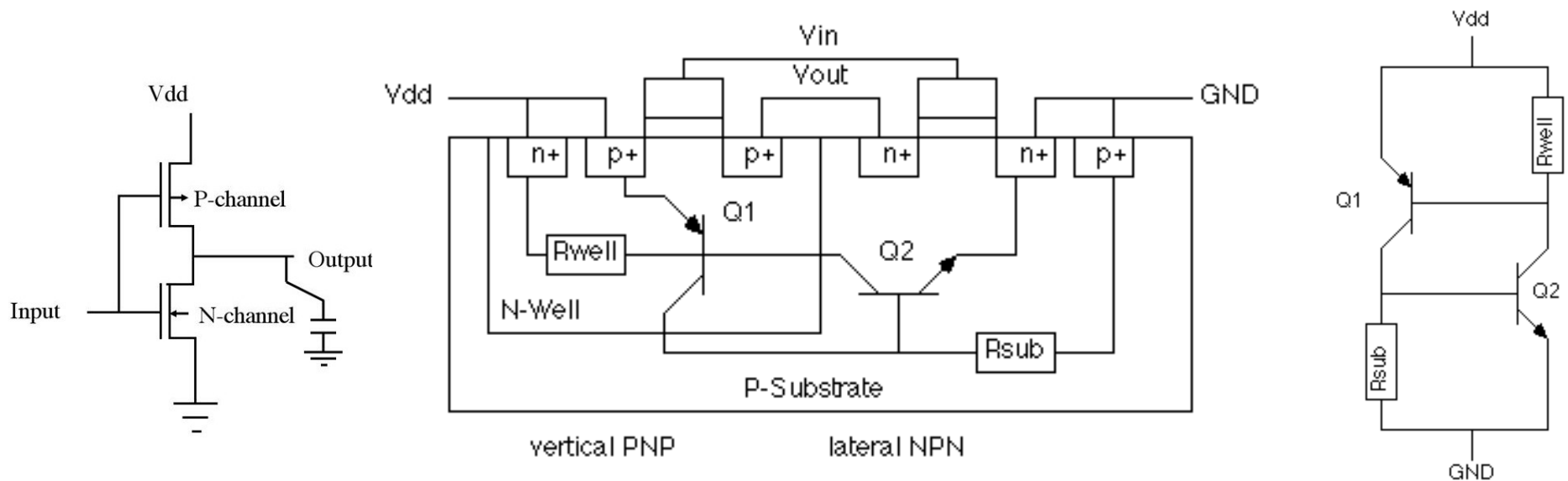


$$\beta_1 * \beta_2 > 1$$

Used for switching high currents or voltages



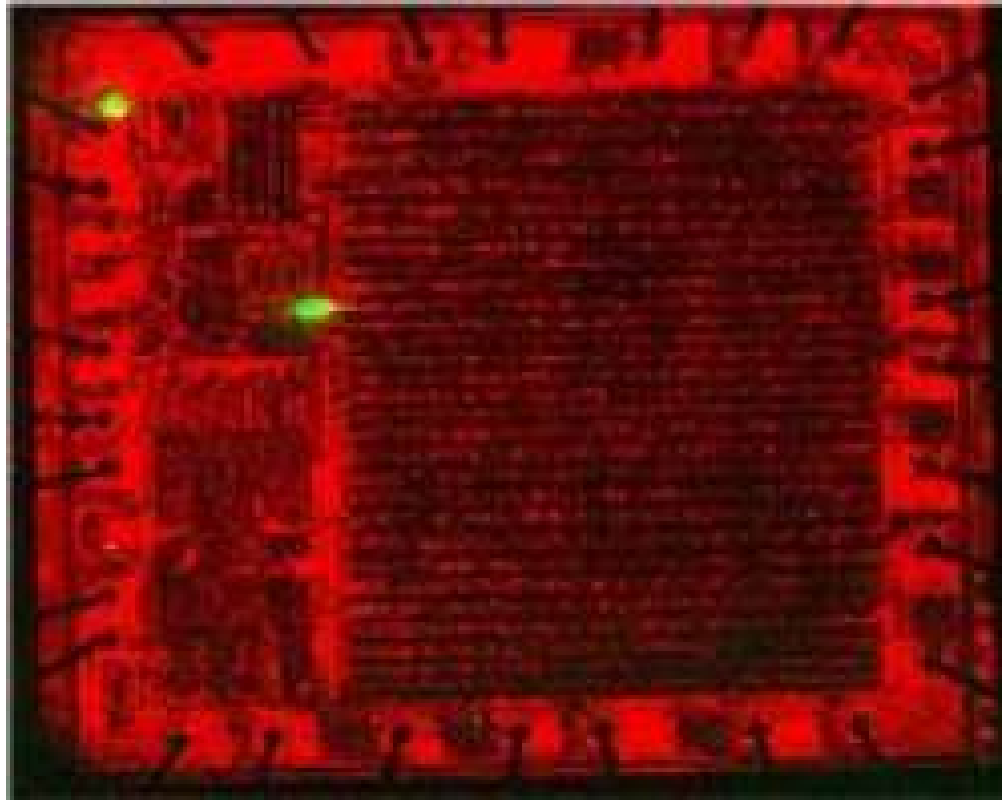
Latch-up



Both BJT's conduct, creating a low resistance path between V_{dd} and GND. The product of the gains of the two transistors in the feedback loop, is greater than one. The result of latchup is at the minimum a circuit malfunction, and in the worst case, the destruction of the device.

<http://www.ece.drexel.edu/courses/ECE-E431/latch-up/latch-up.html>

Emission Microscope



Forward biased diodes emit light. (BJT)
Defects often emit light.

<http://www.muanalysis.com/techniques/emission-microscopy-emmi>

When does it emit light?

Thyristor

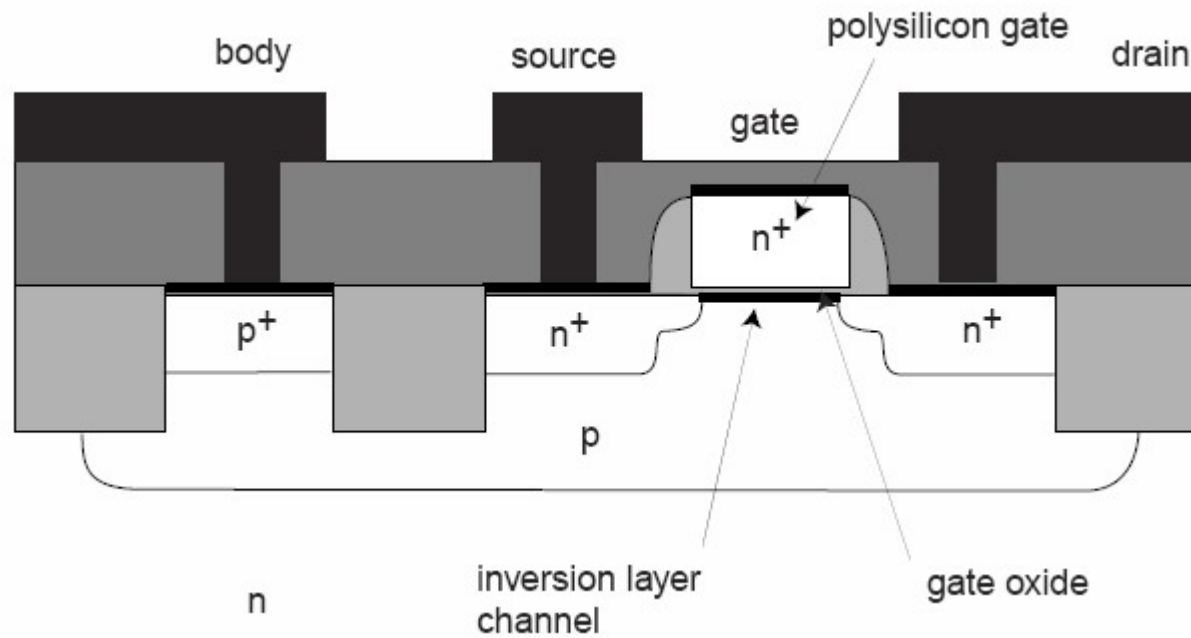
Bipolar junction transistors

MOSFET

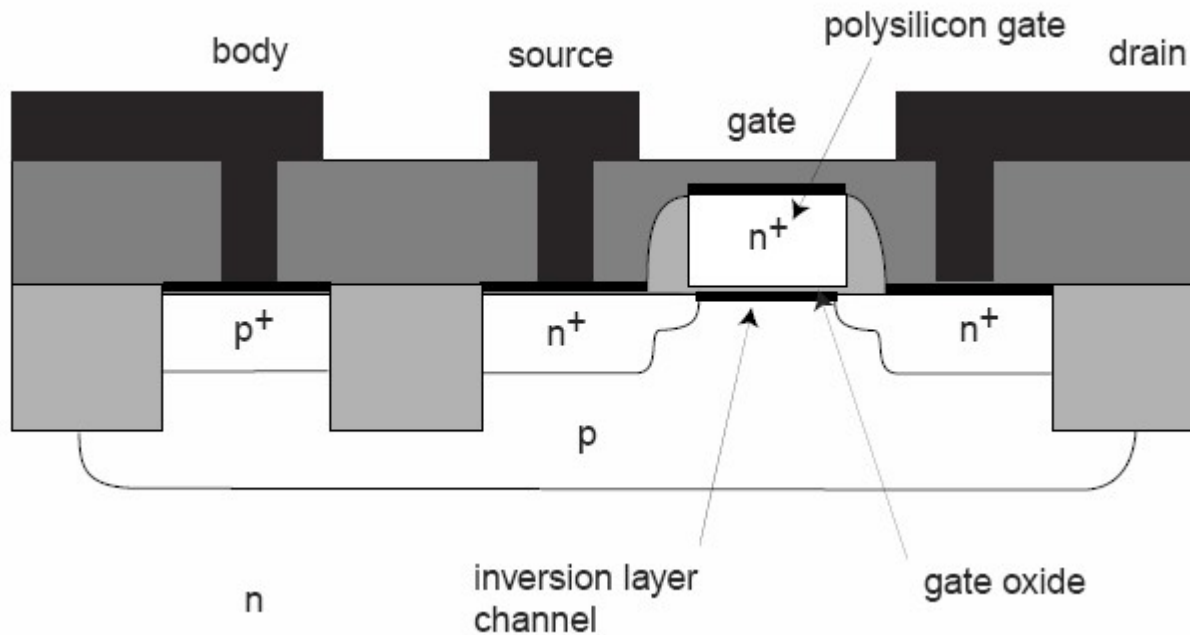
JFET

Si diode

Can you operate like a BJT?



Subthreshold current

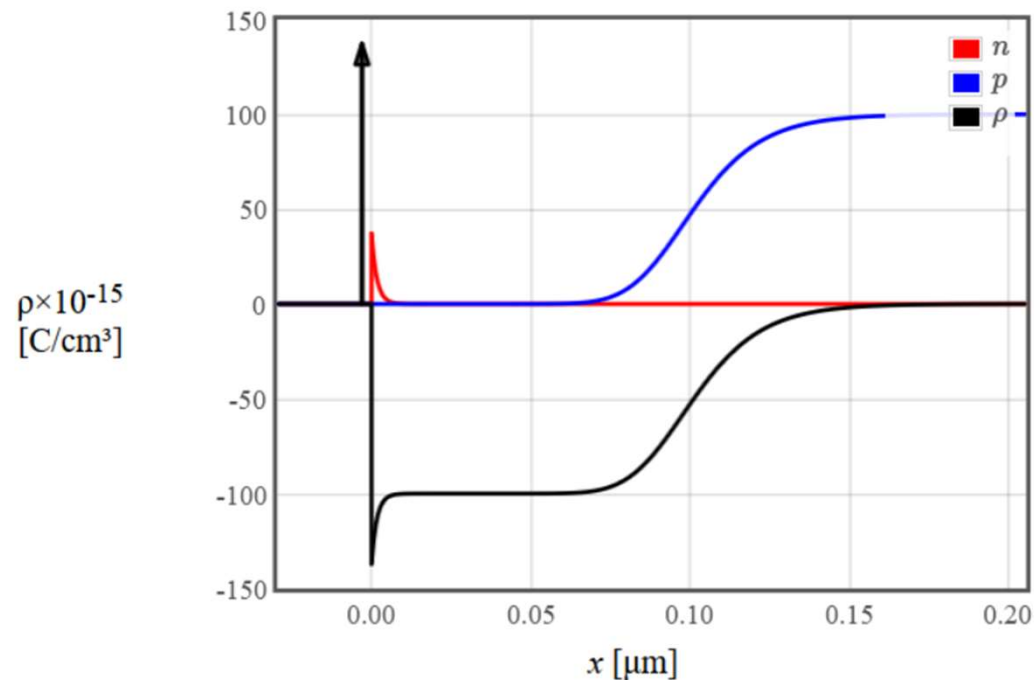


If the p-concentration in the channel is low, electrons emitted into the channel by the forward biased junction diffuse across the channel without recombining.

Subthreshold current – depletion approximation

$$x_p = -\frac{\epsilon_s}{\epsilon_{\text{OX}}} t_{\text{OX}} + \sqrt{\left(\frac{\epsilon_s}{\epsilon_{\text{OX}}} t_{\text{OX}}\right)^2 + \frac{2\epsilon_s}{eN_A} (V_g - V_{fb})}$$

$$n(x) = \begin{cases} \frac{n_i^2}{N_A} \exp\left(\frac{e^2 N_A (x_p - x)^2}{2\epsilon_s k_B T}\right) & \text{for } 0 < x < x_p, \\ \frac{n_i^2}{N_A} & \text{for } x > x_p, \end{cases}$$

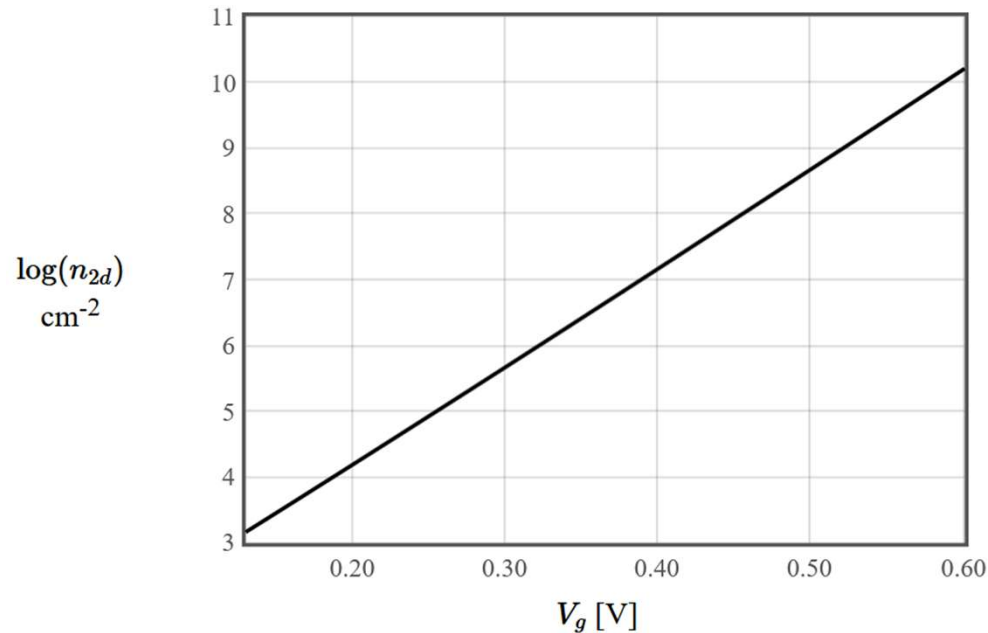


Subthreshold current – depletion approximation

$$n(x) = \frac{n_i^2}{N_A} \exp\left(\frac{e^2 N_A (x_p - x)^2}{2\epsilon_s k_B T}\right)$$

$$n(x) \approx \frac{n_i^2}{N_A} \exp\left(\frac{e^2 N_A (x_p^2 - 2x_p x)}{2\epsilon_s k_B T}\right)$$

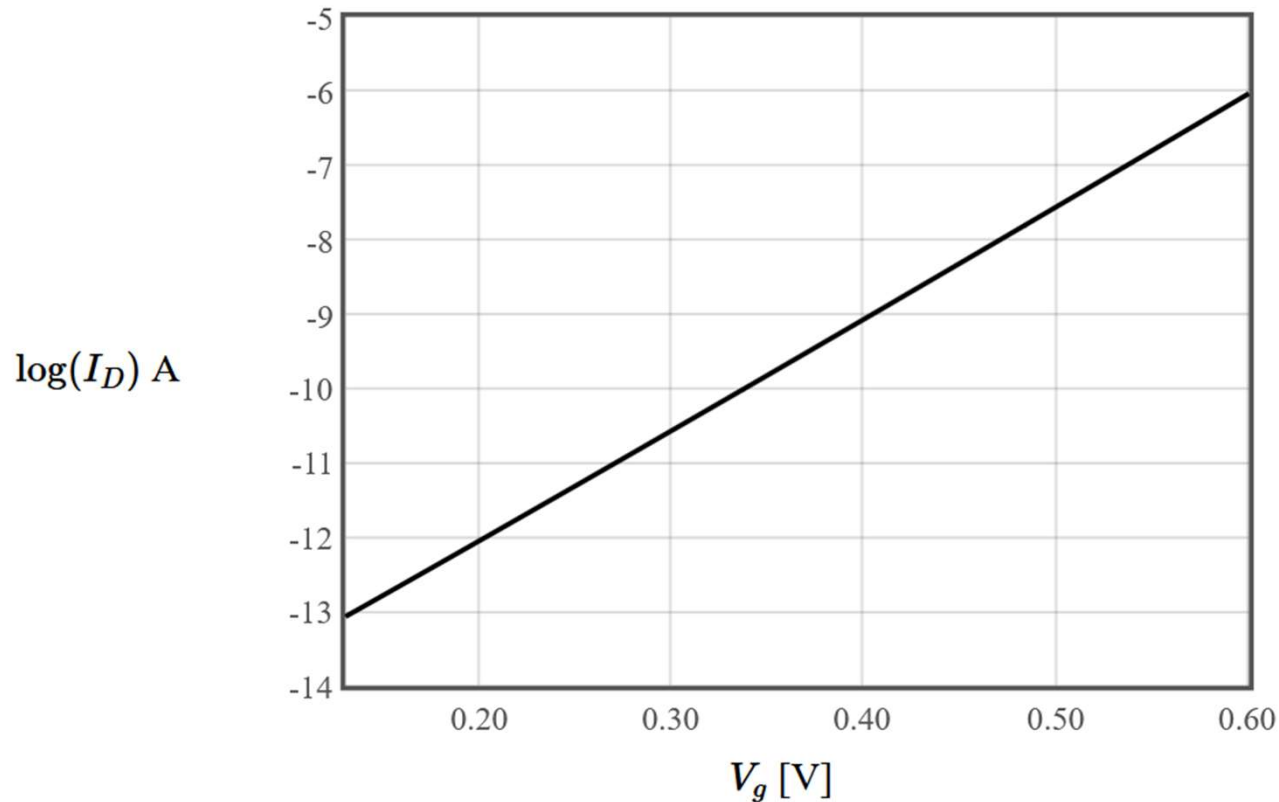
$$n_{2d} = \frac{n_i^2}{N_A} \exp\left(\frac{e^2 N_A x_p^2}{2\epsilon_s k_B T}\right) \frac{\epsilon_s k_B T}{e^2 N_A x_p}$$



Subthreshold current – depletion approximation

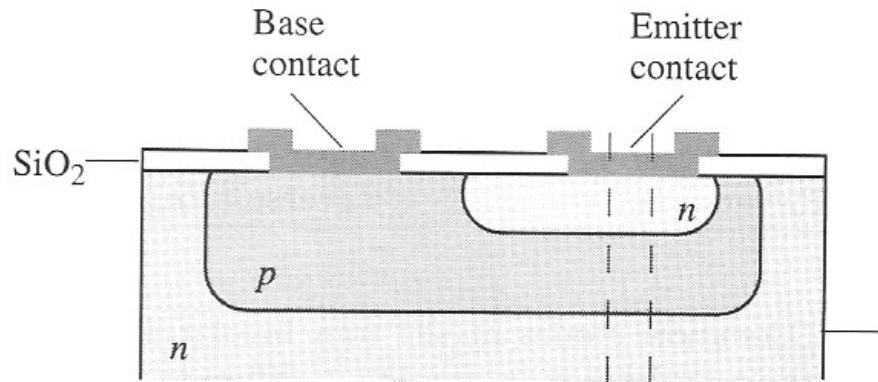
$$\nabla n \approx -\frac{n_{2d}}{L}$$

$$I_D \approx \frac{k_B T \mu W n_{2d}}{L} = \frac{n_i^2 \mu \epsilon_s k_B^2 T^2 W}{e^2 N_A^2 x_p L} \exp\left(\frac{e^2 N_A x_p^2}{2 \epsilon_s k_B T}\right)$$



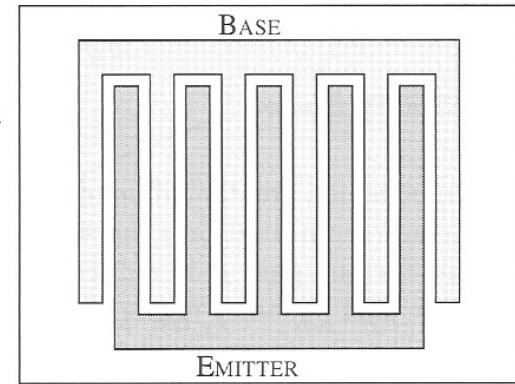
Subthreshold slope: 70-100 mV/decade

Interdigitated contacts in power transistors

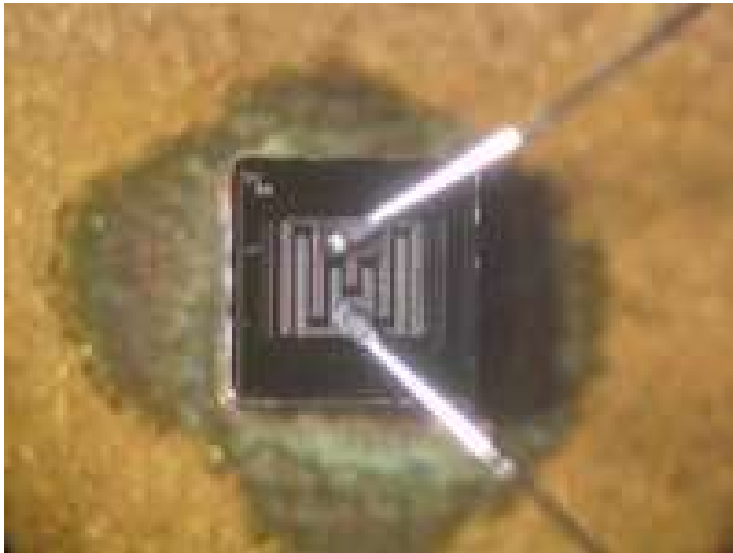
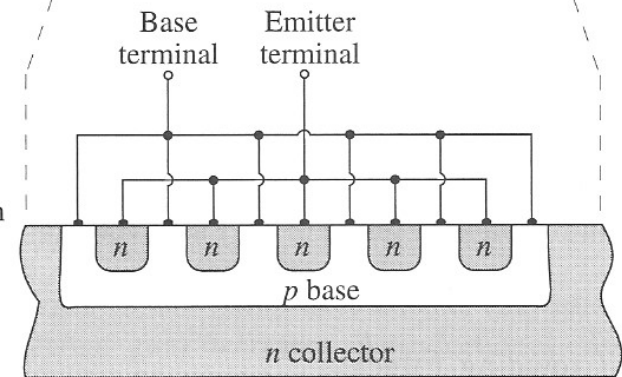


Interdigitated fingers to inject current uniformly into a bipolar device

Top view

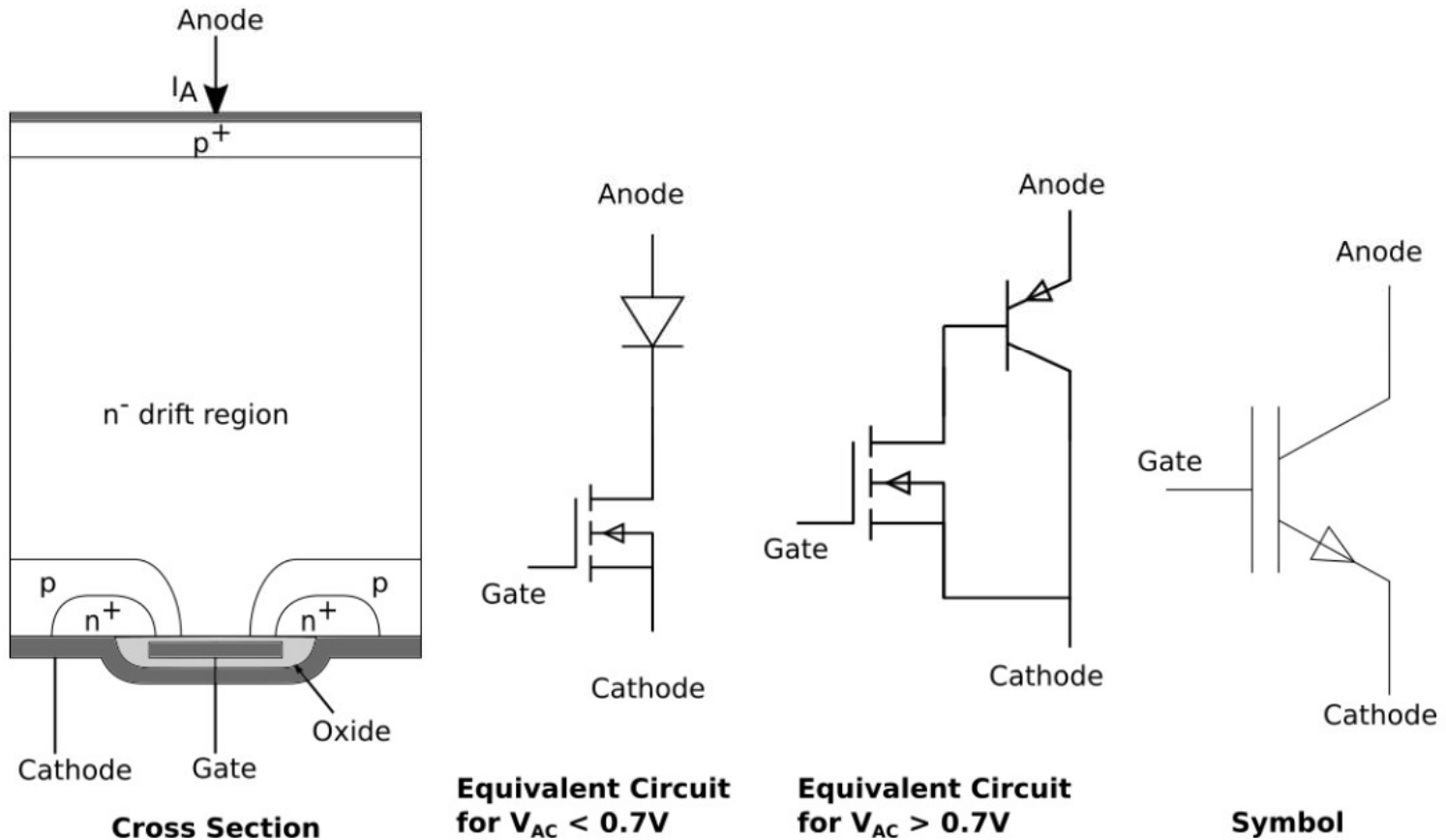


Cross-section



IGBT - Insulated Gate Bipolar Transistor

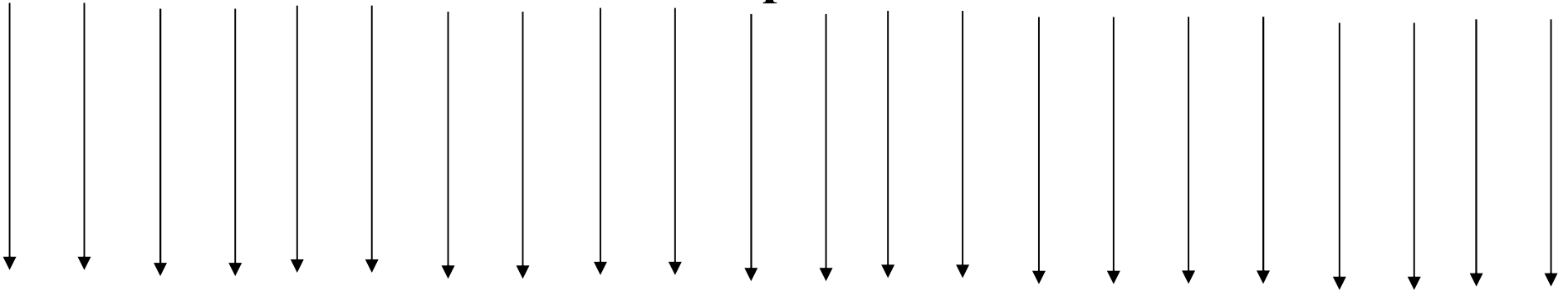
An IGBT is a combination of an insulated gate FET and a bipolar transistor. It is primarily used for switching high power loads



Used to switch large currents (in electric cars or trains).
Like a thyristor for high voltages.

<http://lampx.tugraz.at/~hadley/psd/L13/igbt.html>

Implant



SiO₂

Deposit oxide

Spin resist

Expose

Develop

Etch Oxide

Strip resist

Implant subcollector n+

p-Si

Antimony (Sb) has a low vapor pressure and won't evaporate during the subsequent CVD step

Epi-growth

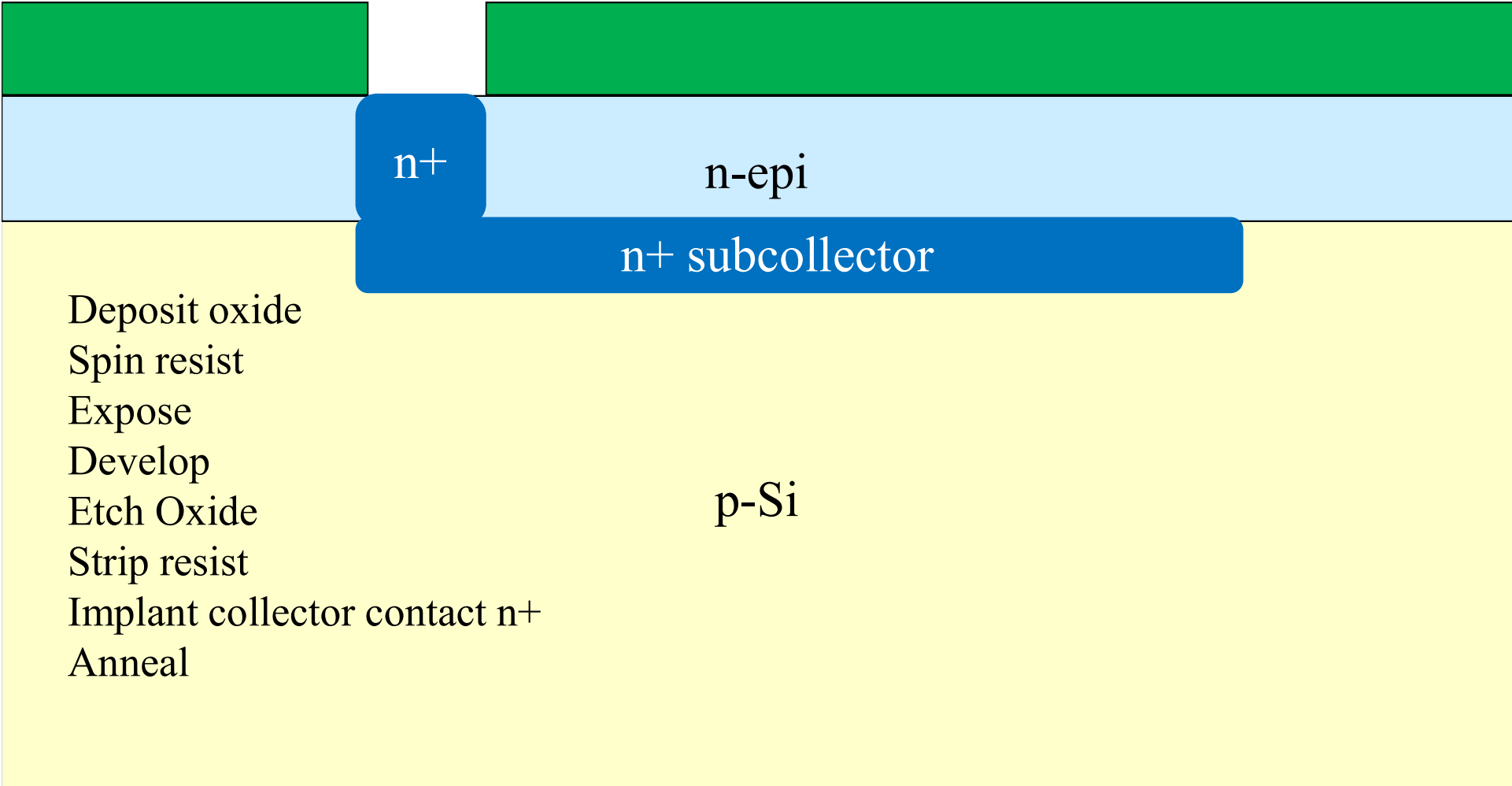
n-epi

n+ subcollector

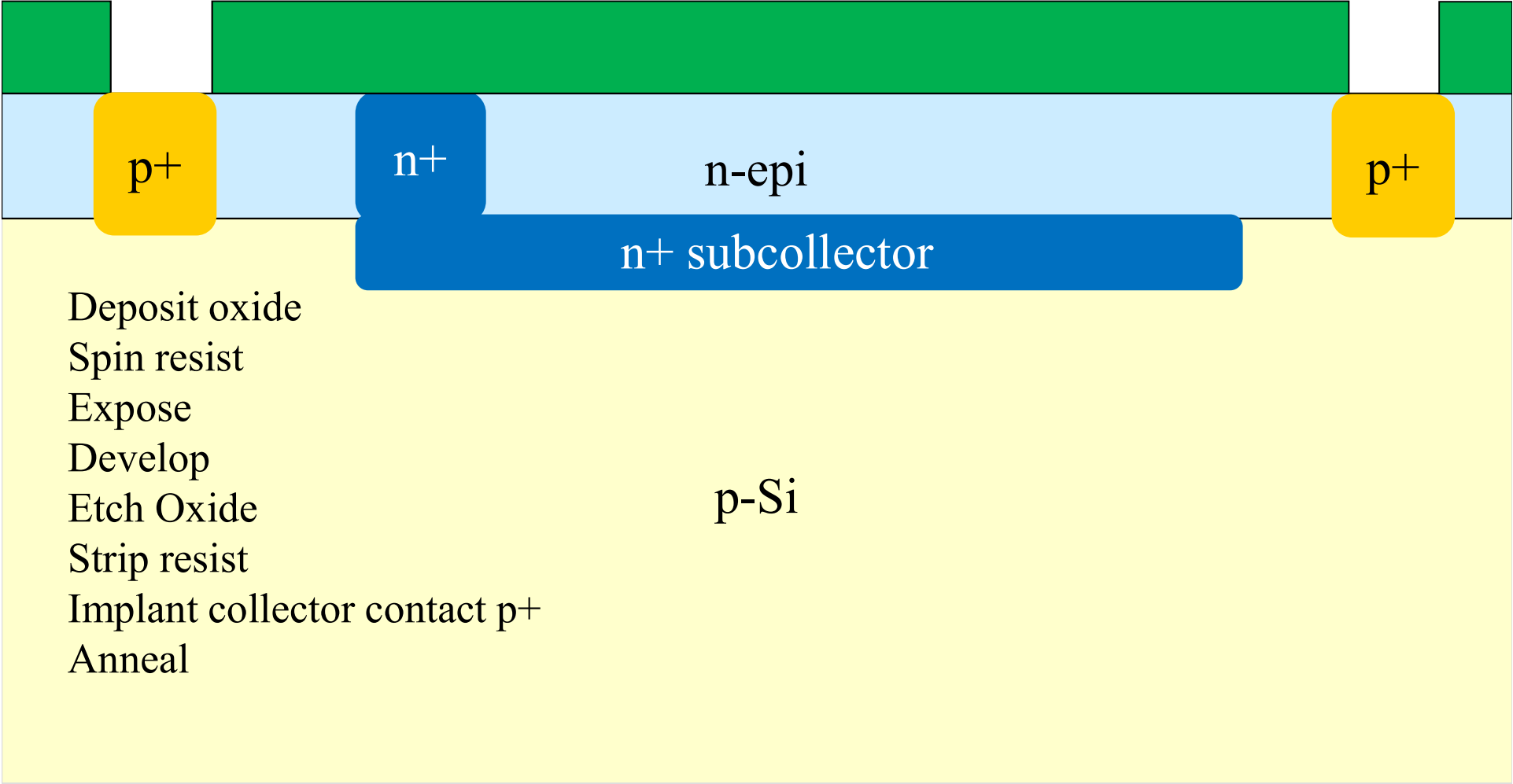
Remove oxide
Clean surface
Silicon epitaxy
CVD $\text{SiH}_4 + \text{PH}_3$

p-Si

Collector Contact

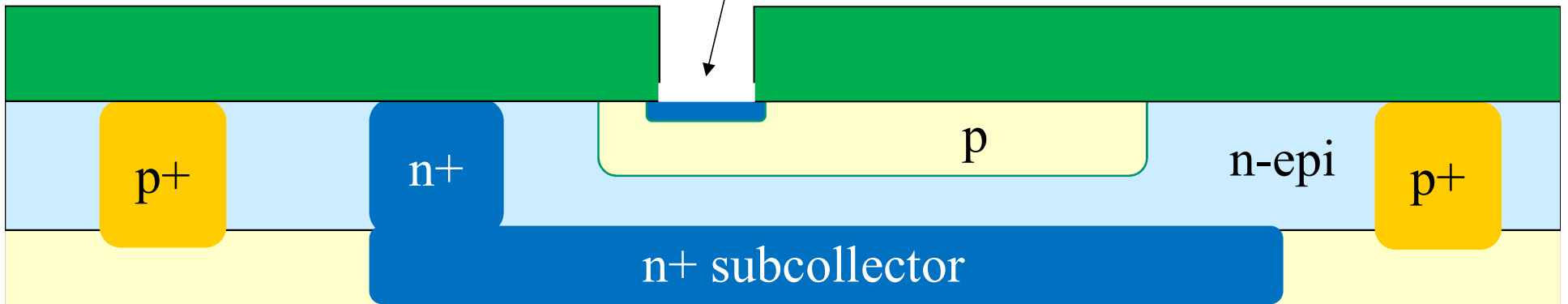


Guard ring



- Deposit oxide
- Spin resist
- Expose
- Develop
- Etch Oxide
- Strip resist
- Implant collector contact p+
- Anneal

n+ emitter



- Deposit oxide
- Spin resist
- Expose
- Develop
- Etch Oxide
- Strip resist
- Implant base
- Anneal

p-Si

BiCMOS

Only one additional step to CMOS is needed for BiCMOS

Bipolar junction transistors:
high speed
high gain
low output impedance
good for analog amplifiers

CMOS
high impedance
low power logic

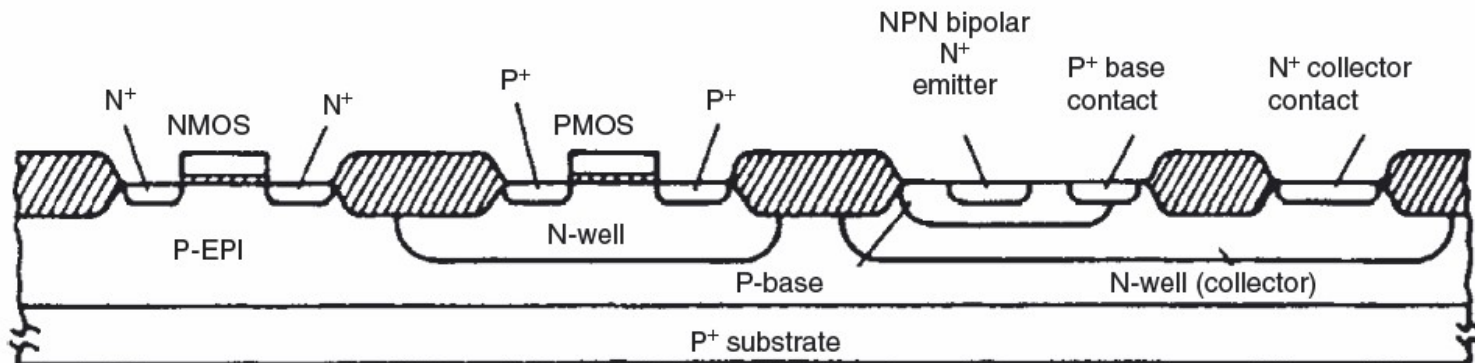


Figure 27.6 Simple BiCMOS technology: triple diffused-type bipolar transistor added to a CMOS process with minimal extra steps: only p-base diffusion mask is added to CMOS process flow. Reproduced from Alvarez (1989) by permission of Kluwer

Fransila

See: http://www.iue.tuwien.ac.at/phd/puchner/node48_app.html

Optoelectronics

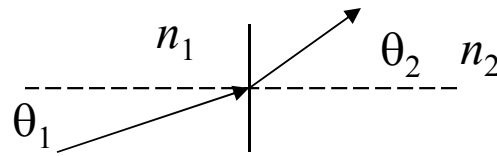
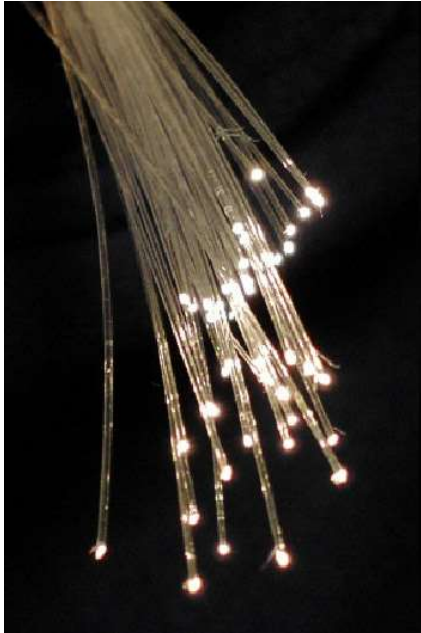
Optoelectronics

light emitting diode
laser diode
solar cell
photo detectors

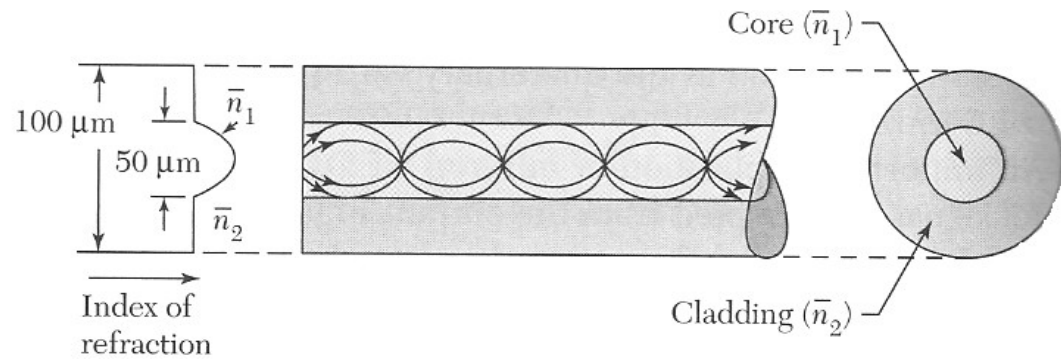
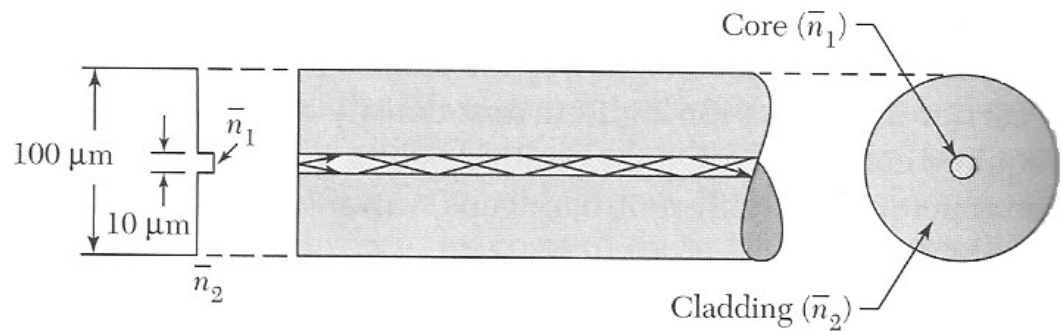


communications, memory (DVD), displays, printing, bar-code readers, solar energy, lighting, laser surgery, measurement, guidance, spectroscopy, LiFi

Confinement of light by total internal reflection



$$n_1 \sin \theta_1 = n_2 \sin \theta_2$$

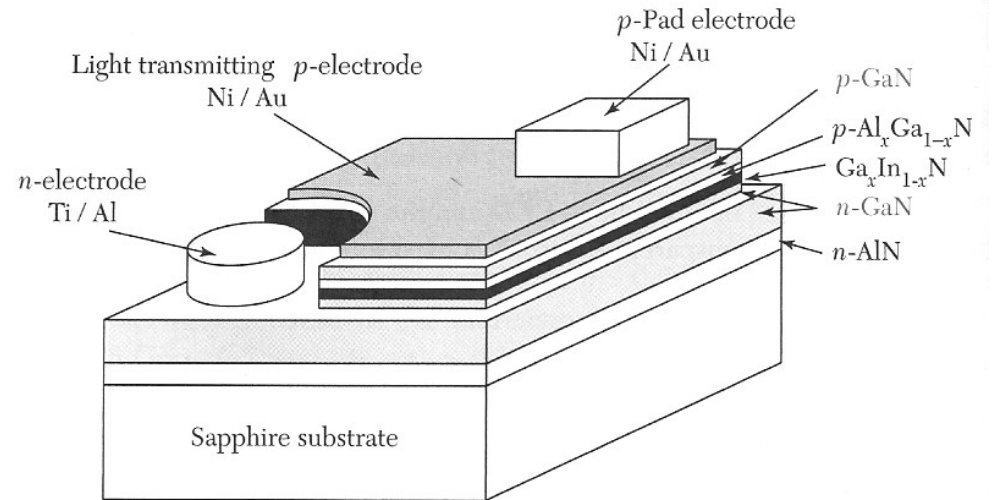
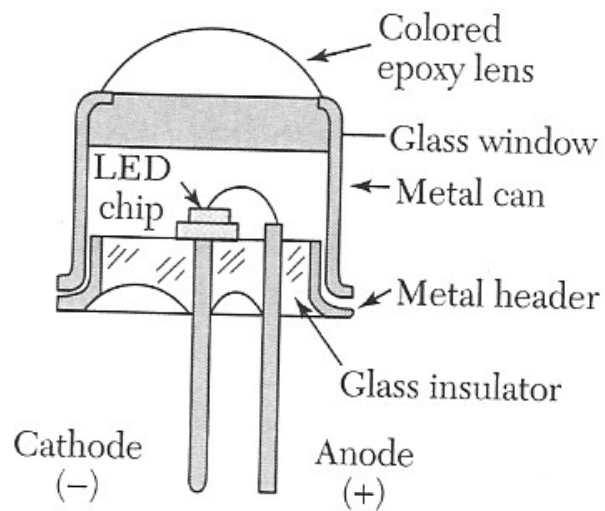
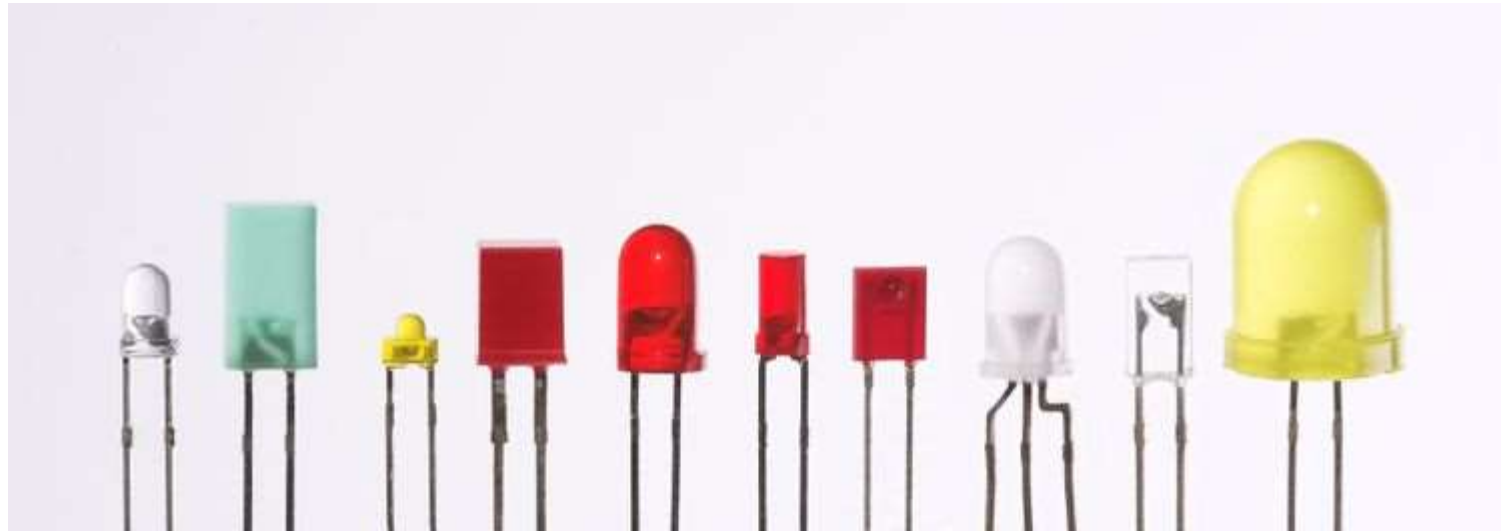
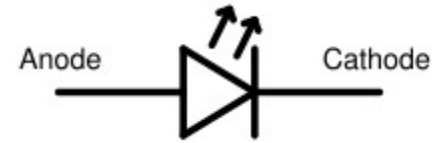


less pulse spreading for parabolically graded fiber

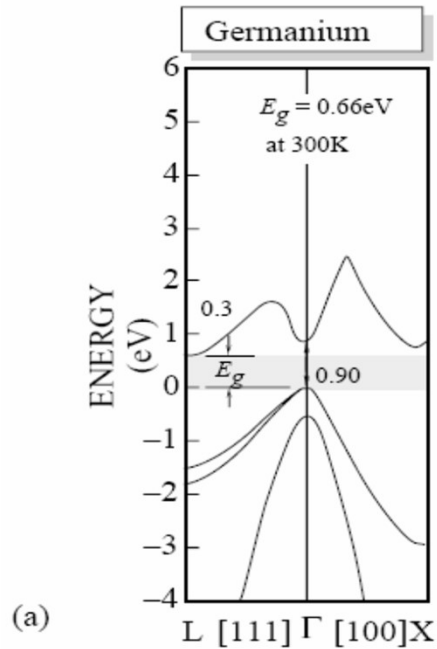


0.6 dB/km at 1.3 μm and 0.2 dB/km at 1.55 μm

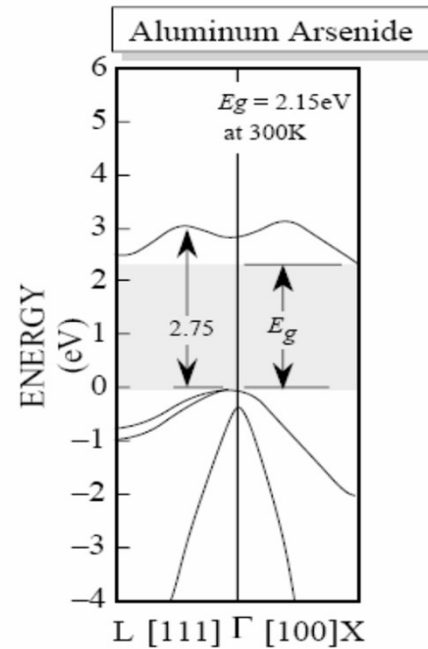
Light emitting diodes



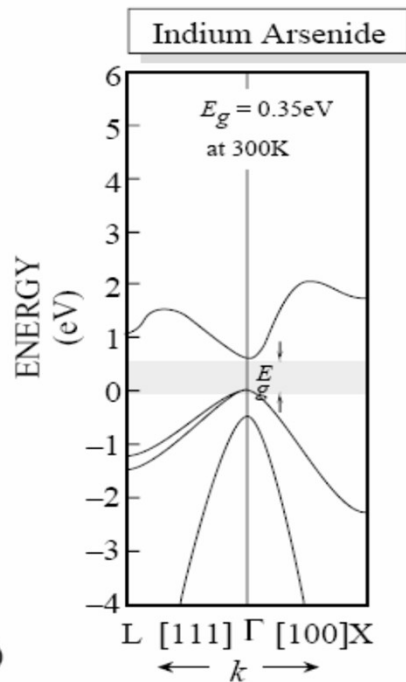
Solid state lighting is efficient.



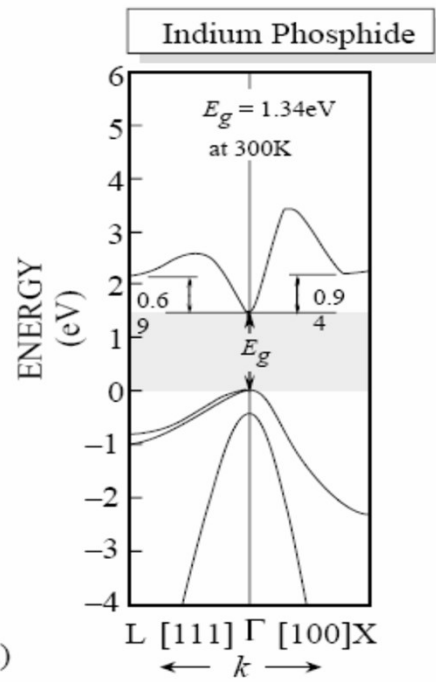
(a)



(b)



(c)



(d)

direct bandgap:
 $\Delta k = 0$

photons can be
emitted

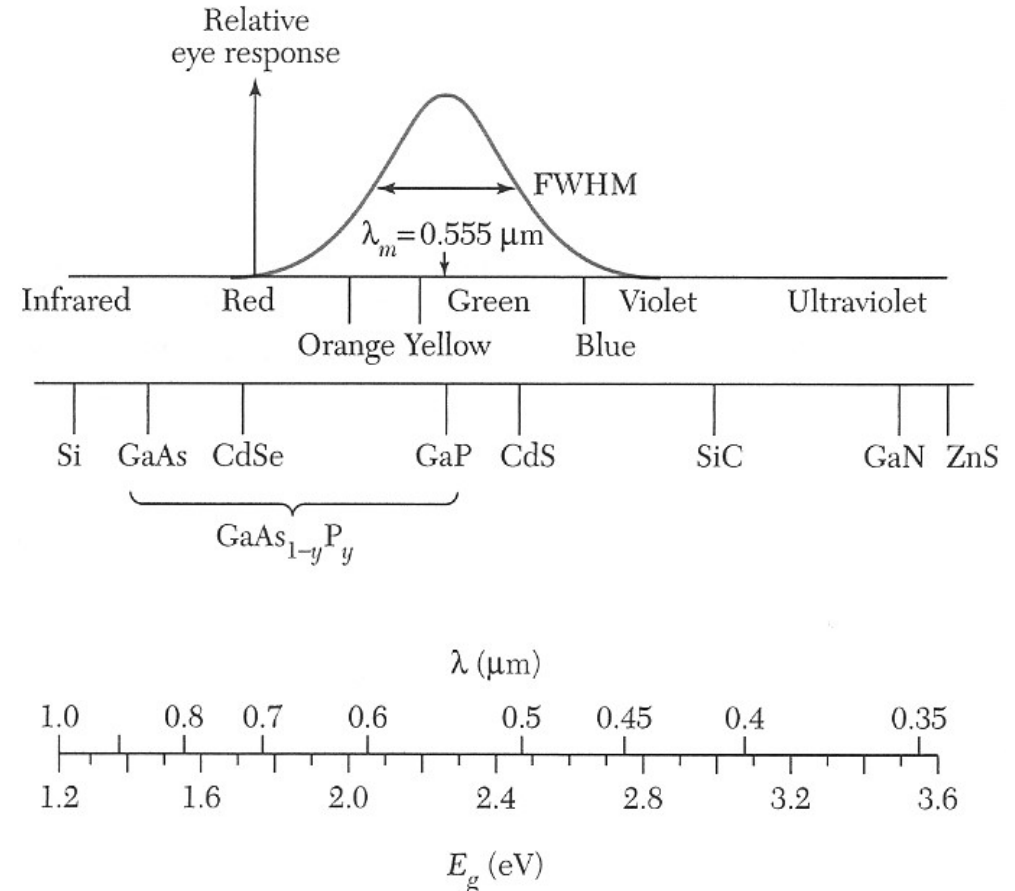
indirect bandgap:
 $\Delta k \neq 0$

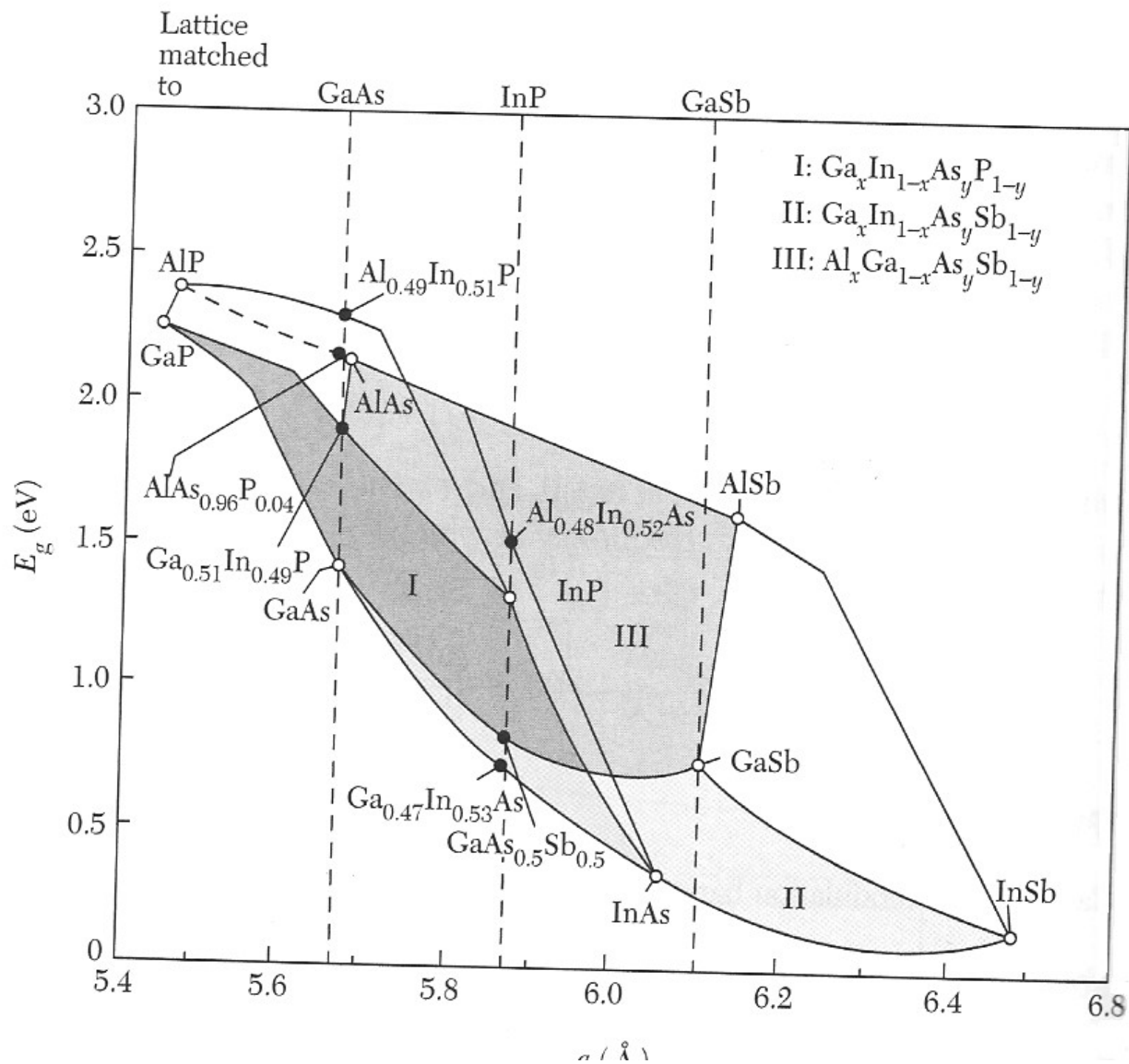
phonons are
emitted

TABLE 1 Common III-V materials used to produce LEDs and their emission wavelengths.

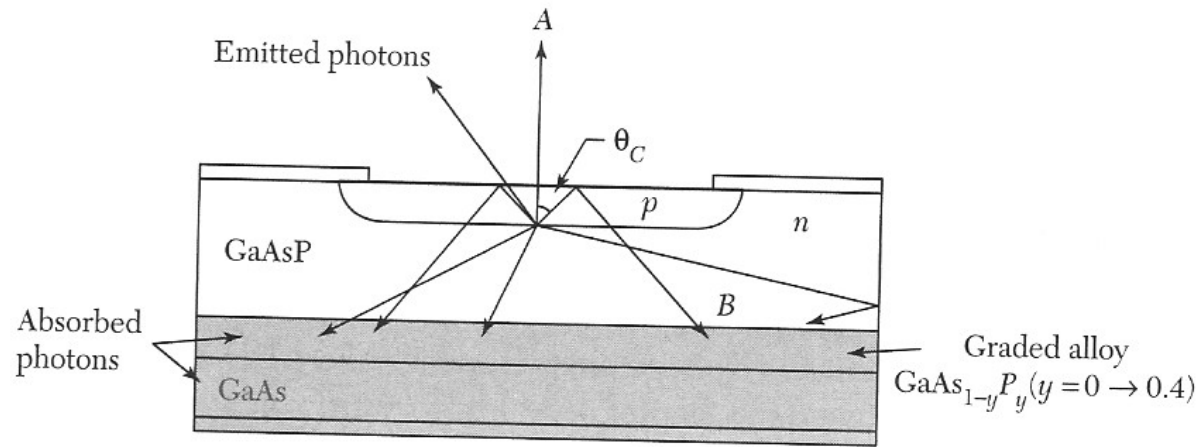
Material	Wavelength (nm)
InAsSbP/InAs	4200
InAs	3800
GaInAsP/GaSb	2000
GaSb	1800
$Ga_xIn_{1-x}As_{1-y}P_y$	1100-1600
$Ga_{0.47}In_{0.53}As$	1550
$Ga_{0.27}In_{0.73}As_{0.63}P_{0.37}$	1300
GaAs:Er, InP:Er	1540
Si:C	1300
GaAs:Yb, InP:Yb	1000
$Al_xGa_{1-x}As:Si$	650-940
GaAs:Si	940
$Al_{0.11}Ga_{0.89}As:Si$	830
$Al_{0.4}Ga_{0.6}As:Si$	650
$GaAs_{0.6}P_{0.4}$	660
$GaAs_{0.4}P_{0.6}$	620
$GaAs_{0.15}P_{0.85}$	590
$(Al_xGa_{1-x})_{0.5}In_{0.5}P$	655
GaP	690
GaP:N	550-570
$Ga_xIn_{1-x}N$	340,430,590
SiC	400-460
BN	260,310,490

Light emitting diodes

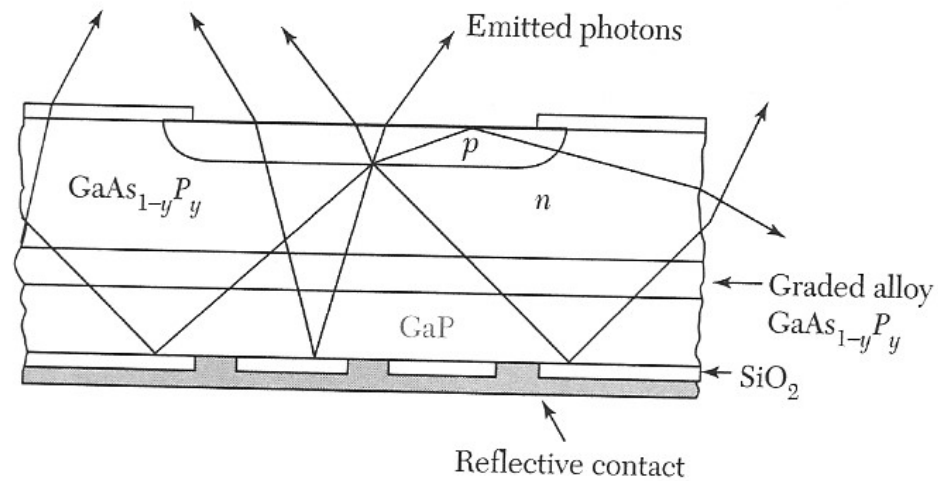




Light emitting diodes





absorption
reflection
total internal reflection

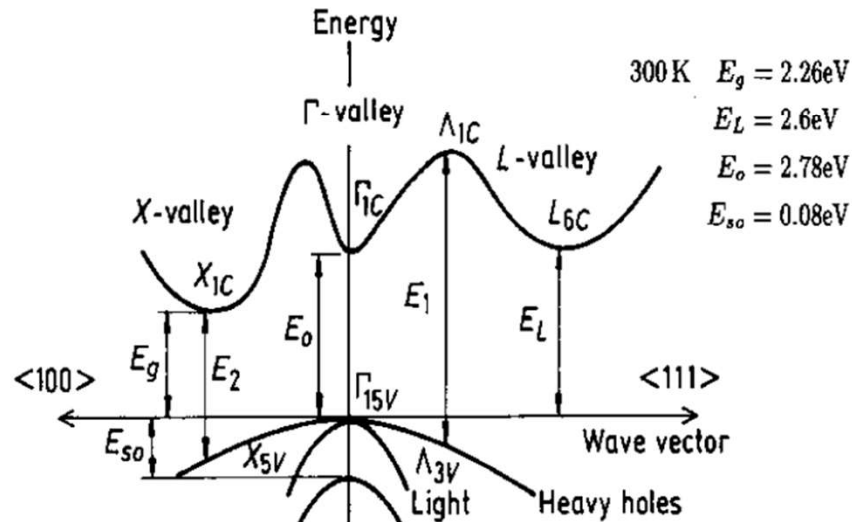


Light Emitting Diode

A Light Emitting Diode (LED) consists of a pn-diode in a semiconductor with a direct bandgap. When the diode is forward biased, the electrons and the holes are pushed towards the junction where they recombine. The photons that are emitted have the energy of the band gap, $E_g = \frac{hc}{\lambda}$. The slider below lets you select a wavelength. The corresponding bandgap to this wavelength is calculated and the approximate color is shown. For some bandgap energies, the composition of a direct bandgap semiconductor that will emit this wavelength is shown.

$\lambda = 650 \text{ nm}$  $E_g = 1.91 \text{ eV}$ visible  $\text{Al}_{0.39}\text{Ga}_{0.61}\text{As}$ $\text{GaAs}_{0.39}\text{P}_{0.61}$

Below, simplified band diagrams can be displayed for some semiconductors. The electrons in the conduction band are primarily located at the minimum of the conduction band and the holes in the valence band are concentrated at the maximum of the valence band. The electrons are thermally excited up to about $k_B T$ above the conduction band minimum and the holes are excited to about $k_B T$ below the valence band maximum. When the electrons and holes recombine, this results in photon energies approximately in the range $E_g \pm k_B T$.



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- Extrinsic Semiconductors
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- pn junctions
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- MOSFETs
- Bipolar transistors
- Opto-electronics
- Lectures
- Books
- Exam questions
- Html basics
- TUG students
- Student projects
- Print version

Photo detectors

Intrinsic semiconductor $\sigma = e(\mu_n n + \mu_p p)$ (used in copiers)

Unbiased pn junction - like a solar cell

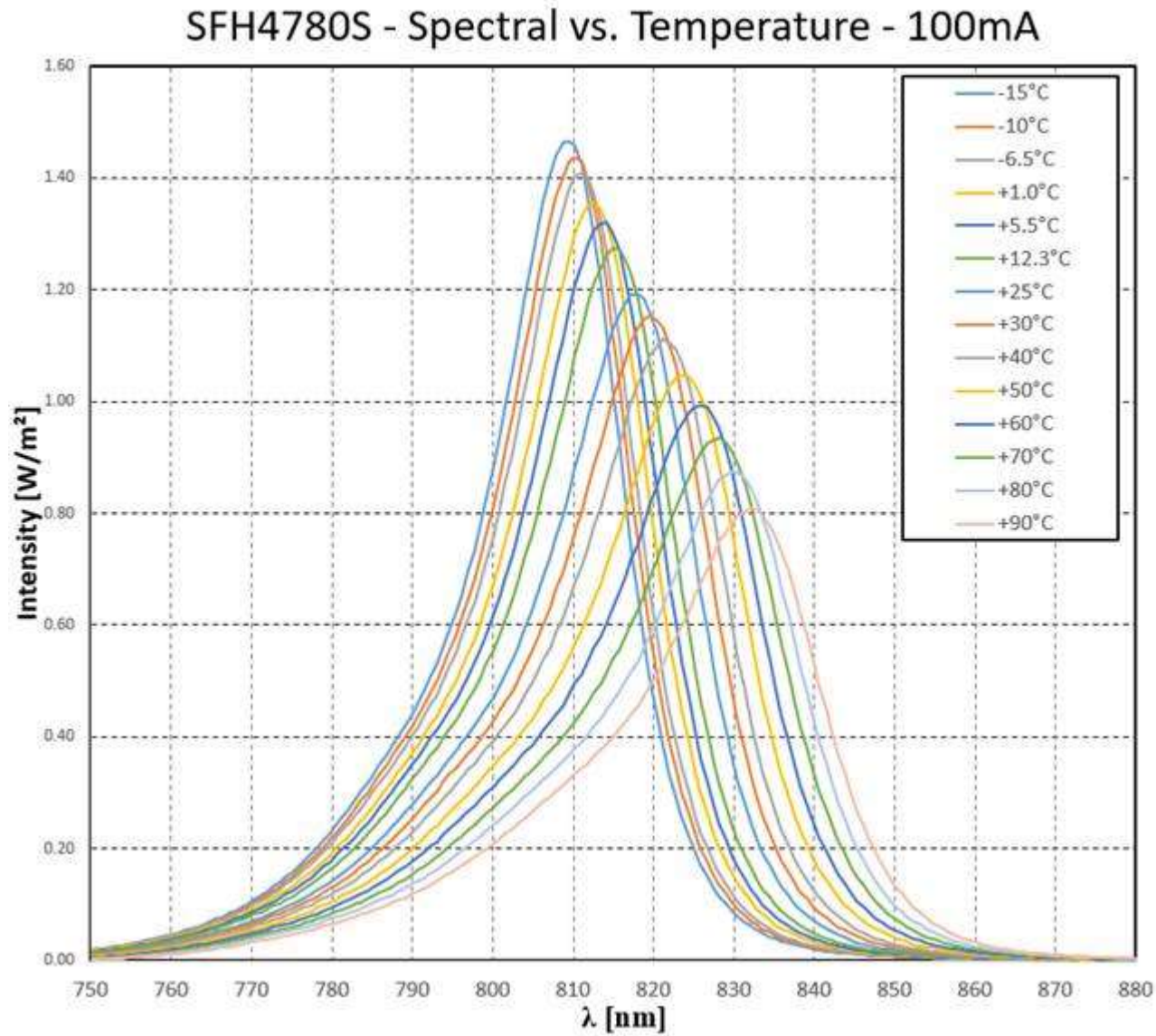
Reverse biased pn junction - smaller capacitance, higher speed, less noise

Phototransistor - light injects carriers into the base. This forward biases the emitter base junction. High responsivity.

Ambient light detectors.

Active Pixel sensors for automated parking and gesture control (uses time-of-flight to image in 3-D).

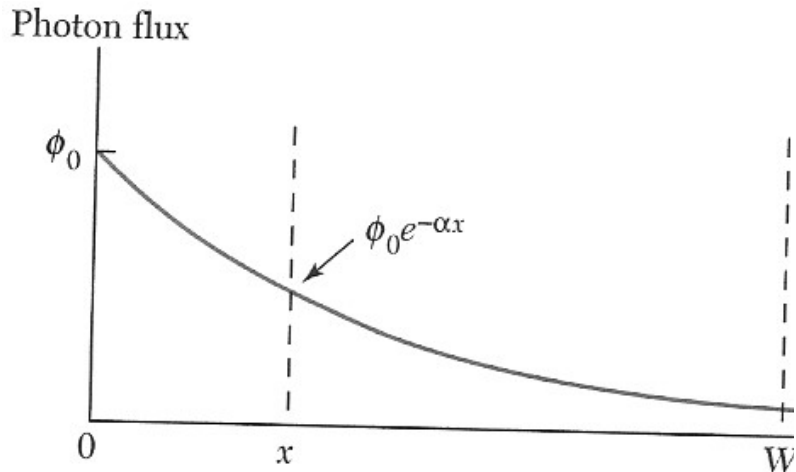
IR LED



Measurement by Jan Enenkel

Absorption

Photon flux: $\Phi(x) = \Phi_0 e^{-\alpha x}$

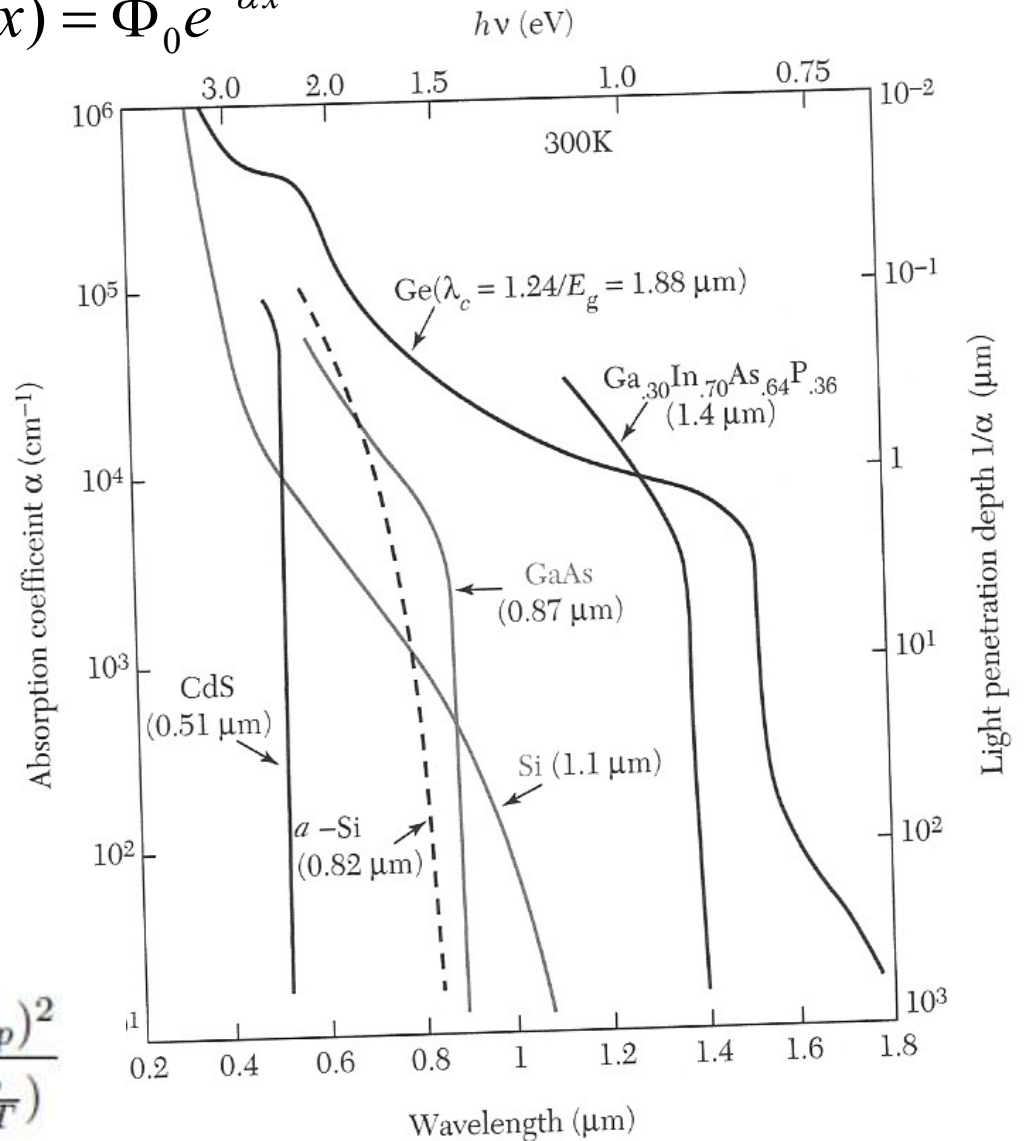


Sharp absorption edge for direct bandgap materials

$$\alpha \approx 3.5 \times 10^6 \left(\frac{m_r^*}{m_0} \right)^{3/2} \frac{\sqrt{\hbar\omega - E_g}}{\hbar\omega} \text{ cm}^{-1}$$

direct bandgap indirect bandgap

$$\alpha \propto \frac{(h\nu - E_g + E_p)^2}{\exp(\frac{E_p}{k_B T}) - 1} + \frac{(h\nu - E_g - E_p)^2}{1 - \exp(-\frac{E_p}{k_B T})}$$



AS7420 64-channel hyperspectral near infrared sensor

Typical Spectral Responsivity of Sensor

